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(71) Applicant: **TOSHIBA CORP**

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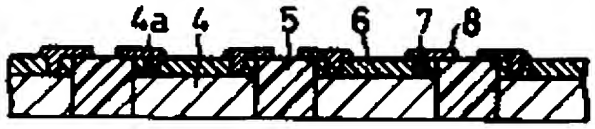
(74) Representative:

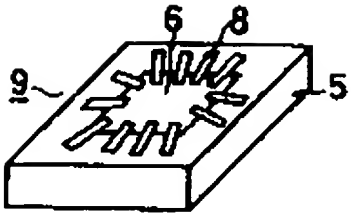
(54) MANUFACTURE OF SEMICONDUCTOR CARRIER

(57) Abstract:

PURPOSE: To improve the productivity, by burying a semiconductor chip in a package consisting of side members provided by insulator frames and of an upper member provided by an insulation layer, and by connecting an electrode pad on the chip to input/output terminals of a carrier through a conductor pattern.

CONSTITUTION: A semiconductor wafer 1 is cut off on a flexible support sheet 3 into separate chips 4. Insulator frames 5, which will be side members of a semiconductor carrier, are mounted in the gaps defined between the chips 4 so as to fill the gaps and to fix the chips positionally. An insulation layer 6, which will be a surface member, is then deposited on the chip. The insulation layer 6 is melt selectively above an electrode pad 4a on the chip 4 so as to provide an opening 7. Conductor patterns 8 are then formed on the surfaces of the insulator frames 5 and insulation layer 6 such that they are connected to the electrode pad 4a of the semiconductor chip through the opening 7 formed in the insulating layer 6. Finally, the insulator frame 5 is cut off between the





semiconductor chips 4 so that semiconductor carriers 9 each consisting of one chip are obtained.

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